

## ABSTRACT OF THE DISCLOSURE

An image sensor includes plural lower metal sheets, plural upper metal sheets stacked on the lower metal sheets, and an encapsulant for encapsulating the lower and upper metal sheets, wherein the upper surfaces of the upper metal sheets are exposed from the encapsulant, the lower surfaces of the lower metal sheets are exposed from the encapsulant, and the encapsulant is formed with a frame layer around the upper surfaces of the upper metal sheets to define a chamber together with the upper metal sheets. The image sensor further includes a photosensitive chip arranged within the chamber, plural wires for electrically connecting the chip to the upper surfaces of the upper metal sheets, and a transparent layer arranged on the frame layer to cover the chip.